providing a pre-form assembly comprising a base layer and a sacrificial layer, the base layer comprising wire or solder paste through conductors, or the base layer comprising a fiber mesh material impregnated with a thermoset;

applying the pre-form assembly to either the IC or supporting surface;

peeling away the sacrificial layer;

sandwiching the [peeled pre-form assembly] base layer between the IC and the supporting surface; and

curing the base layer.

14. The method of claim 13 wherein providing the preform assembly comprises:

providing a sacrificial layer;

coating the sacrificial later with a release coating;

applying a thermosetting material on top of the release coating;

curing the thermosetting material to form a B-stage layer; and

inserting through conductors into the thermosetting material.

15. The method of claim 14 wherein the step of inserting through conductors into the thermosetting material comprises either piercing wires into the thermosetting material, or lasing or drilling and subsequently filling holes in the thermosetting material with a solder paste.

22. (Added) The method of claim 14 wherein the release coating at least partially comprises silicon, Teflon®, or graphite release agents.

23. (Added) The method of claim 13 wherein the base layer comprises a fine mesh fiber material impregnated with a thermoset, and the fine mesh fiber is thermally conductive.

24. (Added) The method of claim 13 wherein the base layer comprises a fine mesh fiber material impregnated with a thermoset and the fine mesh fiber is electrically non-conductive.